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Precious Metals Joining

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TECHNICAL DATA SHEET

Date
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Product Name:	**NFA**
Product Description:	NFA is a fluoride-free, general-purpose system for soldering gold, silver and copper based alloys, as well as most steels. Works well with all gold and silver solders. This paste is a specialty system that is designed for precise placement and to prevent movement of small parts during the early heating of the assembly. It is ‘sticky’ and does not spread when heated so it can help self fixture small parts. The drawback to this paste is that it can dry out if left open for extended periods (overnight). The paste can usually be reconstituted by stirring, or in cases of severe drying the appropriate thinner can be added (see Reference Documents below). This product works best with slightly aggressive heating techniques with more focus of the torch on the paste deposit after the binder has burned off. It is also suitable for use with resistance and induction soldering techniques, and has limited use in furnace soldering. The paste deposit is restrictive and will not spread when heated before the flux begins to melt. The flux in this product is not very fluid and will tend to stay localized once it begins to melt. Flux residues are slightly more tenacious than our standard paste fluxes, but can still be removed with a water quench after soldering, by cleaning with warm soapy water once cool, via ultrasonic, or by agitation.
Metal Percentage:	Typical metal content is 55-70% metal powder by weight.
Working Range:	1000-1600°F
Suitable Filler Metals:	This producted has been tested with most silver brazing alloys, gold solder alloys and copper-phosphorous brazing alloys with good results.
Reference Documents:	Material Safety Data Sheet: MSDS-NFC.pdf Using Paste Solder: usingpaste.pdf Thinning Paste: thinningpaste.pdf